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| (30) Priority:  | (71) Applicant: <b>OKI ELECTRIC IND CO LTD</b> |
| (43) Date of application publication: <b>12.08.94</b> | (72) Inventor: <b>MATSUMURA KAZUO</b>          |
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**(54) DEVICE FOR PLATING  
BUMP ELECTRODE OF  
SEMICONDUCTOR WAFER****(57) Abstract:**

**PURPOSE:** To suppress the plating shape inferiority of a semiconductor wafer by making a jet nozzle, put in a plating vessel, rectangular, and dividing the interior, and providing each with an anode electrode, and connecting a wave guide tube for plating to the inflow port of each nozzle divided.

**CONSTITUTION:** A plating vessel 31 and a jet nozzle 32 are rectangular, and even in a semiconductor with a large bore, the jet of plating liquid contacts uniformly with the inside of the semiconductor wafer. Moreover, the oblong jet nozzle 32 is divided into plural, and each is provided with an anode electrode 33. The number of pumps 45 for circulation jet is equal to that of the divided jet nozzles 32. The level by this pump for circulation jet is always detected by a liquid level

detector 49 and is controlled by the group of pumps 35 for circulation. Hereby, plating liquid can always contact uniformly with the semiconductor wafer being an plated object.

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